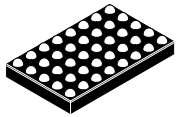


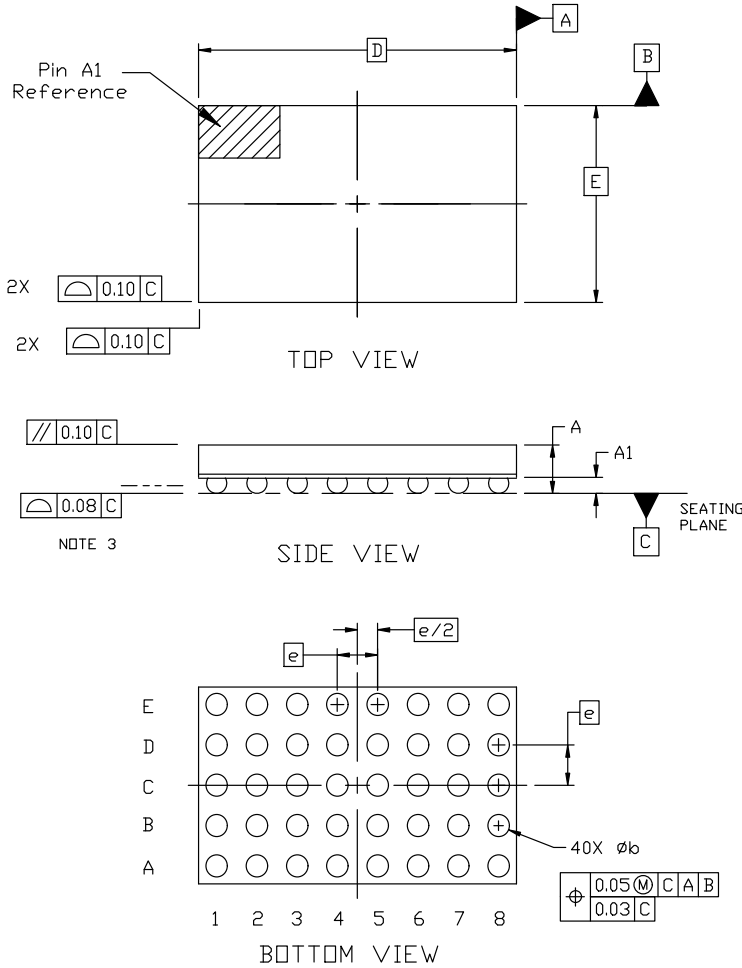
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

WLCSP40, 2.44x3.94
CASE 567JB
ISSUE A

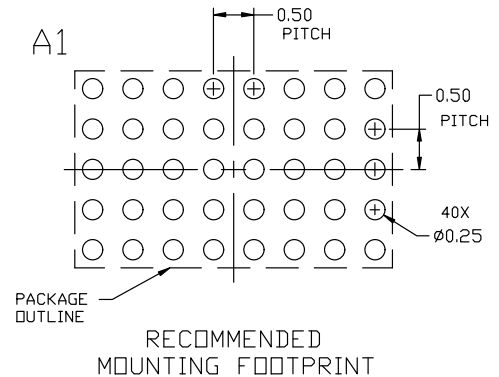
DATE 20 DEC 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.65
A1	0.14	0.24
b	0.22	0.32
D	3.94 BSC	
E	2.44 BSC	
e	0.50 BSC	



* For additional information on our Pb-Free strategy and soldering details, please download the [DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D](#).

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DESCRIPTION:	WLCSP40, 2.44X3.94	PAGE 1 OF 1

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